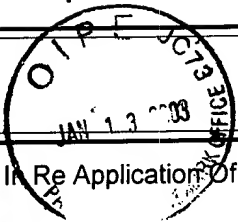


2827



**TRANSMITTAL LETTER  
(General - Patent Pending)**

Docket No.  
**END920000187US1**

In Re Application Of: **Richard R. Hall et al.**

Serial No.	Filing Date	Examiner	Group Art Unit
09/884,778	06/19/2001	Dinh, Tuan T.	2827

Title: **METHOD AND APPARATUS TO ESTABLISH CIRCUIT LAYERS INTERCONNECTIONS**

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TO THE COMMISSIONER OF PATENTS AND TRADEMARKS:

Transmitted herewith is:

**Amendment  
Postcard**

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457 (IBM)** as described below. A duplicate copy of this sheet is enclosed.
  - ☐ Charge the amount of \_\_\_\_\_
  - ☒ Credit any overpayment.
  - ☒ Charge any additional fee required.

Dated: **1/7/2003**

**Arlen L. Olsen  
Reg. No. 37,543  
SCHMEISER, OLSEN & WATTS  
3 Lear Jet Lane, Suite 201  
Latham, NY 12110  
(518) 220-1850**

I certify that this document and fee is being deposited on **1/7/2003** with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

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Applicants: Richard R. Hall *et al.*

Examiner: Dinh, Tuan T.

Serial No.: 09/884,778

Art Unit: 2827

Filed: 06/19/2001

Dkt. No.: END920000187US1

For: **METHOD AND APPARATUS TO  
ESTABLISH CIRCUIT LAYERS INTERCONNECTIONS**

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Commissioner for Patents  
Washington, D.C. 20231

Sir:

This paper is being filed in response to the Final Office Action mailed November 7, 2002.

Applicant respectfully requests that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

**In The Specification:**

Please delete the abstract and insert the following:

--An interconnect formed between layers of a circuit board, wherein a conductive element is embedded in an opening within a laminate of the circuit board, and wherein the conductive element forms at least one contact pad extending beyond a surface of the laminate.--

**In The Claims**

Claims 21-24 and 27-37 are pending in the application and are rejected.

Serial No. 09/884,778